



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Hall et al.

Serial No.: 10/785,122

Filed: February 24, 2004

For: UNDERFILLED, ENCAPSULATED
SEMICONDUCTOR DIE ASSEMBLIES
AND METHODS OF FABRICATION

Confirmation No.: 1653

Examiner: J. Diaz

Group Art Unit: 2815

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AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

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Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the specification begin on page 2 of this paper;

Amendments to the Abstract appear on page 4 of this paper; and

Remarks start at page 5 of this paper.